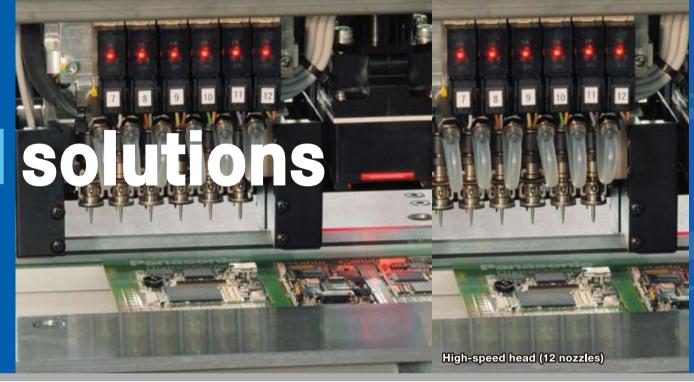
**Electronics Assembly System** catalog

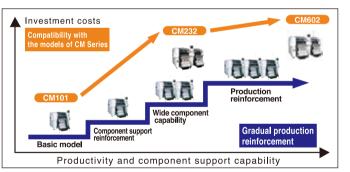
**Our Solutions, Your Value** 

## right-sized solut





Incremental capacity with continuous evolution support



- Ultimate incremental capacity
- · Increase machines with production growth · Compatibility enforces continuity with the
- latest technical developments
- · Commonality assures light investment

## Safety Cautions

Please read the User's Manual carefully to familiarize yourself with safe and effective usage procedures.

■ To ensure safety when using this equipment all work should be performed according to that as stated in the supplied Operating Instructions, Read your operating instruction manual thoroughly,



Panasonic Group products are built with the environment in mind. http://panasonic.net/eco/



Panasonic Group builds Environmental Management System in the factories of the world and acquires the International Environmental Standard ISO 14001:2004.

Inquiries..

## Panasonic Factory Solutions Co., Ltd. Corporate Sales Division

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All data as of December 1, 2011 Ver December 1, 2011



- Unites technologies of our industry-leading CM-series into a lean modular solution
- Flexible solution accommodates production variations with ease
- Minimal investment for quick ROI Compatible with other CM-series equipment



\* It may not conform to Machinery Directive and EMC Directive in case of optional configuration and custom-made specification.

Model ID	CM101-D		
Model No.	NM-EJM5B		
PCB dimensions	L 50 mm × W 50 mm to L 460 mm × W 360 mm		
●High-speed head	12 nozzles		
Max. speed	0.144 s/chip (Type A-2)		
Placement accuracy	± 40 µm/chip (Cpk≥1)		
Component dimensions	(01005") 0402 chip *1 to L 12 mm × W 12 mm × T 6.5 mm		
High-flexibility head	LS8 nozzles		
Max. speed	0.19 s/chip (Type A-0)		
Placement accuracy	± 50 µm/chip, ± 35 µm/QFP □24 mm to □50 mm, ± 50 µm/QFP < □24 mm (Cpk ≥ 1)		
Component dimensions	(01005") 0402 *1 chip to L 100 mm × W 50 mm × T 15 mm *5		
Multi-functional head	3 nozzles		
Max. speed	0.8 s/QFP (Type B-0)		
Placement accuracy	± 35 µm/QFP (Cpk ≥1)		
Component dimensions	(0201") 0603 chip to L 100 mm × W 90 mm × T 25 mm ∗6		
PCB exchange time	about 4.0 s (When no components are placed on the back of the PCB)		
Electric source	3-phase AC 200, 220, 380, 400, 420, 480 V 1.4 kVA		
Pneumatic source *2	0.5 MPa, 150 L /min (A.N.R.)		
Dimensions *2	W 1 530 mm × D 1 807 mm × H 1 430 mm *3		
Mass *4	1 720 kg		

may vary depending on operating conditions.

\*1:The 0402 chip requires a specific nozzle/feede

\*3:Excluding monitor and signal tower

\*4:Only for main body. This may depend on option.

\*5:When T is more than 11.5mm, special nozzles are needed. Please consult us separately

\*6:When T is more than 21mm, special nozzles are needed. Please consult us separately

● Changes in specifications and appearance may be made without notice for product improvement. ● Recycled paper is used this Catalog. •Homepage http://panasonic.net/pfsc/



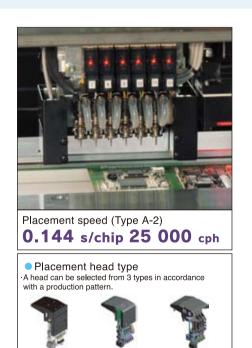
High-speed multi-functionality with 1 beam and 1 head

Enhanced productivity of microchips

Includes latest functionality for high quality placement

Chip thickness measuring sensor (Optional)

For High-speed head (12 nozzles



High-flexibility head

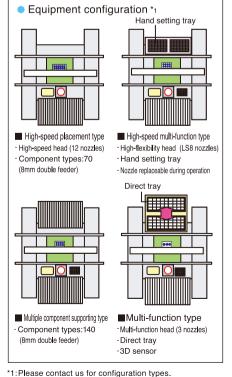
(LS8 nozzles)

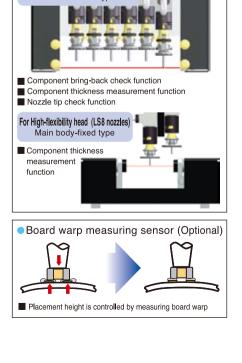
Multi-function hea

(3 nozzles)

■ Type A-2

(12 nozzles)





Concept

- Unites technologies of our industry-leading CM-series into a lean modular solution
- Flexible solution accommodates production variations with ease
- Minimal investment for quick ROI
  - Compatible with other CM-series equipment

High productivity 25 000 cph

Supports up to 40 component types

**Excellent** compatibility

**Incremental Capacity** 

Flexible from high-speed to multi-function pattern support

**Evolution after** installation

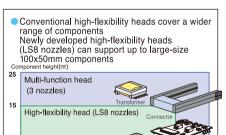
Includes latest component support functionality

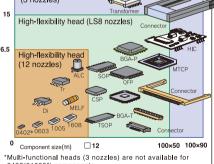


A wide range of components with high-flexibility heads

Multifunctional transfer unit supporting POP and C4

**Excellent compatibility** with CM-series





Achieve multi-functionality at low cost via newly developed



Ceramic nozzle

	Transfer type	Max.dimension
8 nozzles	4 components x two-time batch transfer	□12 mm
3 nozzles	3 components batch transfer	□15 mm

\*High-speed heads (12 nozzles) are not supported

<ul> <li>Highly versatile unit accurately transfers solder/flux for POP top packaging/C4 mounting on the bump side</li> </ul>	<ul> <li>The CM101 is fully compatible with CM-series in accordance with module design concepts</li> </ul>
High-speed POP placement  Transfer material auto-feed	999000
	■Placement head (12·8·3 nozzles) ■ Common nozzles
Placement speed 0.65s/chip Batch transfer for 8 components by high-flexibility heads (LS8 nozzles)  Transfer unit (Optional)	
Maintenance through easy operation	■ Direct tray feeder ■ Feeder cart ■ 3D sensor
	STATE OF
Squeegee Scraper Installation & removal without tools Scraper Installation & removal without tools	■ Tape feeder ■ Bulk feeder ■ Stick feeder (8 mm to 104 mm)
Changeable film thickness Programmable squeegee gap using data Changeable on film thickness each component	(6 iiii (6 104 iiii)
State of the latest and the latest a	■ Touch panel operation ■ Placement data

	Sales of the sales	0000
■Placement head (12·8·3 r	nozzles)	Common nozzles
	HIK W	
■ Direct tray feeder ■ Feed	er cart	■ 3D sensor
	4	-
■ Tape feeder ■ Bulk (8 mm to 104 mm)	feeder	Stick feeder
■ Touch panel operation	■ Pla	cement data